

### Features

Low Forward Voltage Drop  
 Guard Ring Die Construction for  
 Transient Protection  
 Ideal for low logic level applications  
 Low Capacitance

**Lead Free by Design/RoHS Compliant (Note 1)**

**"Green" Device, Note 4 and 5**

**Qualified to AEC-Q101 Standards for High Reliability**

### Mechanical Data

Case: SOD-523

Case Material: Molded Plastic, "Green" Molding  
 Compound, Note 5. UL Flammability Classification  
 Rating 94V-0

Moisture Sensitivity: Level 1 per J-STD-020C

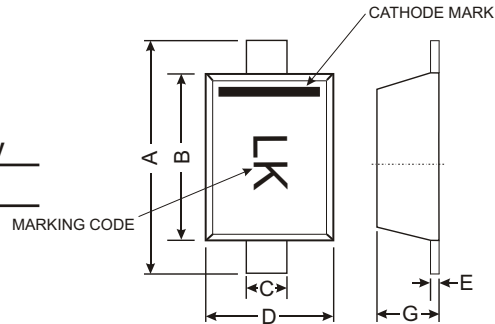
Terminal Connections: Cathode Band

Terminals: Finish - Matte Tin annealed over Alloy 42  
 leadframe. Solderable per MIL-STD-202, Method 208

Marking Code: LK

Ordering Information: See Last Page

Weight: 0.002 grams (approximate)



SOD-523		
Dim	Min	Max
A	1.50	1.70
B	1.10	1.30
C	0.25	0.35
D	0.70	0.90
E	0.10	0.20
G	0.55	0.65
All Dimensions in mm		

### Maximum Ratings @ T<sub>A</sub> = 25 °C unless otherwise specified

Characteristic	Symbol	Value	Unit
Peak Reverse Voltage	V <sub>RM</sub>	40	V
DC Reverse Voltage	V <sub>R</sub>	30	V
RMS Reverse Voltage	V <sub>R(RMS)</sub>	21	V
Average Rectified Current	I <sub>O</sub>	30	mA
Non-Repetitive Peak Forward Surge Current @ 8.3ms Single half sine-wave superimposed on rated load (JEDEC method)	I <sub>FSM</sub>	200	mA
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-40 to +125	°C

### Thermal Characteristics @ T<sub>A</sub> = 25 °C unless otherwise specified

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 2)	P <sub>d</sub>	150	mW
Thermal Resistance, Junction to Ambient (Note 2)	R <sub>JA</sub>	667	°C/W

### Electrical Characteristics @ T<sub>A</sub> = 25 °C unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Conditions
Reverse Breakdown Voltage (Note 3)	V <sub>(BR)R</sub>	40			V	I <sub>R</sub> = 10µA
Forward Voltage (Note 3)	V <sub>F</sub>		290	370	mV	I <sub>F</sub> = 1mA
Peak Reverse Current (Note 3)	I <sub>R</sub>			0.5	A	V <sub>R</sub> = 30V
Total Capacitance	C <sub>j</sub>		2		pF	V <sub>R</sub> = 1V, f = 1.0 MHz

- Note:
1. No purposefully added lead.
  2. Part mounted on FR-4 board with recommended pad layout, which can be found on our website at <http://www.diodes.com/datasheets/ap02001.pdf>.
  3. Short duration pulse test used to minimize self-heating effect.
  4. Diodes Inc.'s "Green" Policy can be found on our website at [http://www.diodes.com/products/lead\\_free/index.php](http://www.diodes.com/products/lead_free/index.php).
  5. Product manufactured with date code 0609 (week 9, 2006) and newer are built with Green Molding Compound. Product manufactured prior to date code 0609 are built with Non-Green Molding Compound and may contain Halogens or Sb2O3 Fire Retardants.

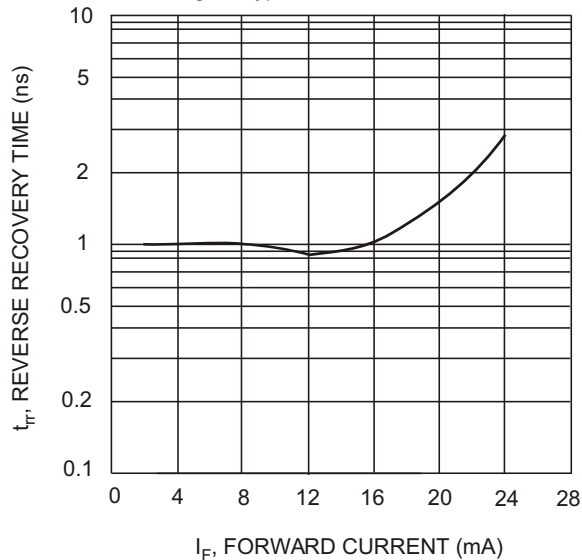
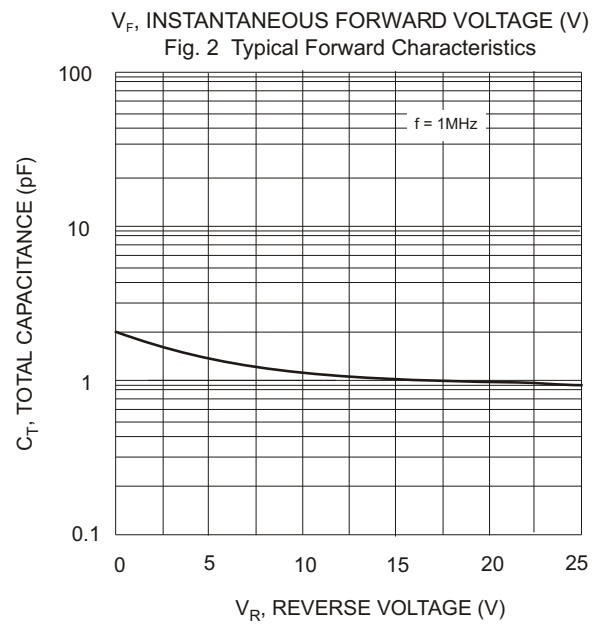
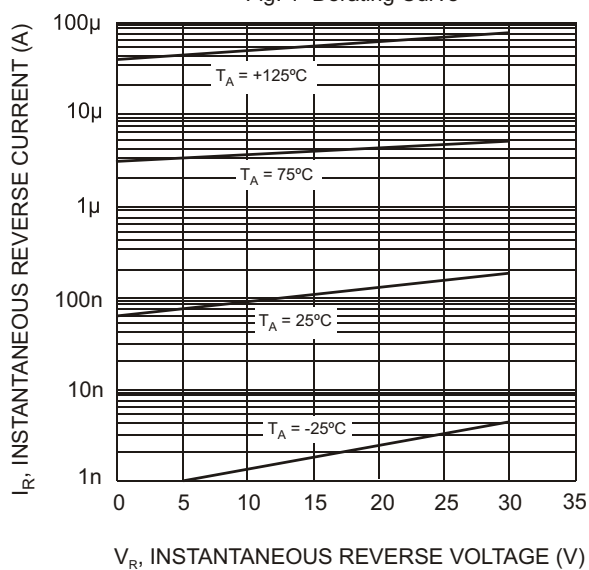
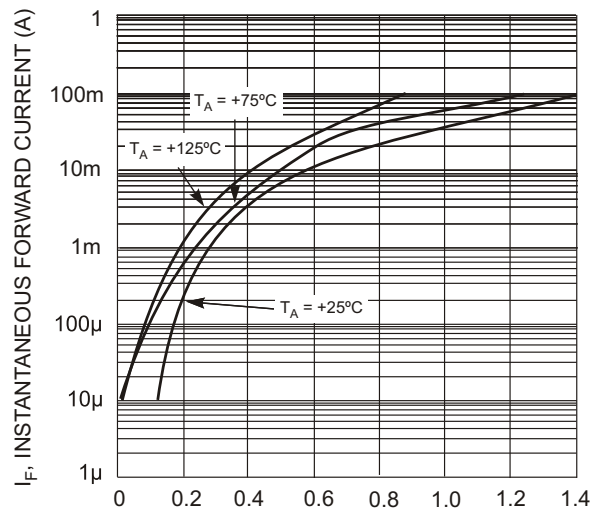
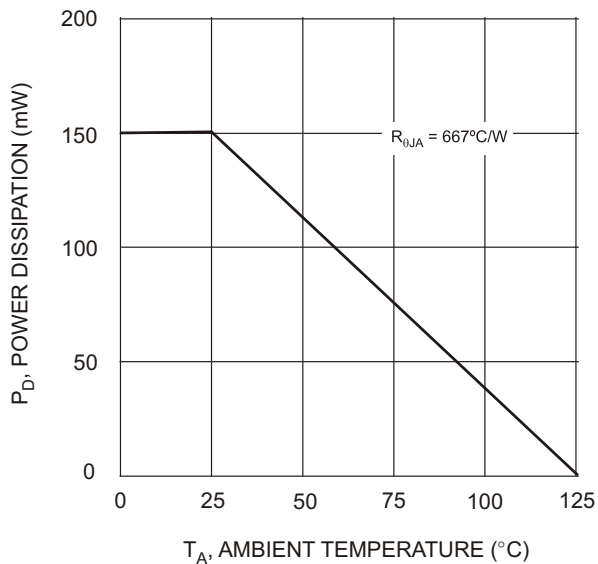


Fig. 5 Typical Reverse Recovery Time Characteristics

**Ordering Information** (Note 5 & 6)

Device	Packaging	Shipping
SDM03U40-7	SOD-523	3000/Tape & Reel
SDM03U40-76K	SOD-523	6000/Tape & Reel

- Note:
- Product manufactured with date code 0609 (week 9, 2006) and newer are built with Green Molding Compound. Product manufactured prior to date code 0609 are built with Non-Green Molding Compound and may contain Halogens or Sb2O3 Fire Retardants.
  - For Packaging Details, go to our website at <http://www.diodes.com/datasheets/ap02007.pdf>.

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